

## Context and objectives

### Abstract

This e-poster presents the design and optimization of a high switching frequency, integrated DC-DC converter. The design target is to convert 3.3 V to 1.2 V, and to supply 280 mA with 90 % efficiency. Preliminary studies are presented, including a technology and a topology evaluation. Based on the results of these studies, a converter using a cascoded power stage has been designed and optimized with a 40 nm Bulk CMOS technology.

The converter die will be flipped on a passive interposer, taking benefits from high performances passive components (trench capacitors and racetracks inductors) and very low package parasitics.

This work is supported by the European Commission through the Seventh Framework Programme (FP7), under the project grant PowerSWIPE n°318529.

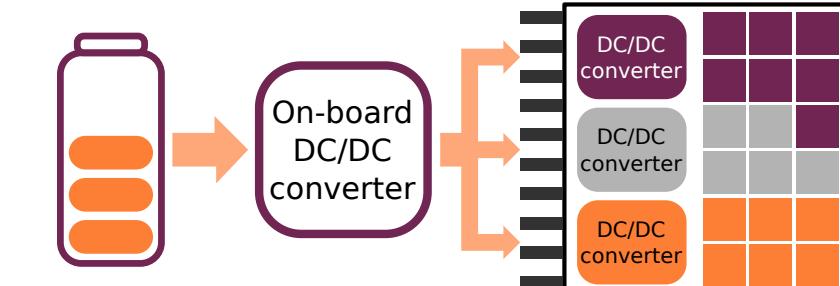


### Increasing the switching frequency

	Area (mm <sup>2</sup> )	Volume (mm <sup>3</sup> )	Frequency (MHz)
50	150	1	
30	25	5	
7.0	3.5	20	
2.0	1.0	50-100	

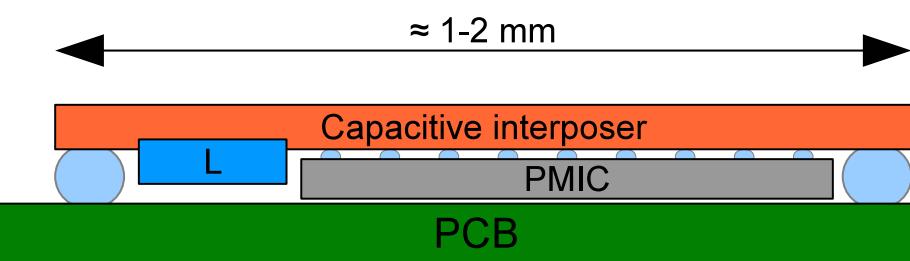
Increasing the switching frequency allows to use passive components (inductors and capacitors) with smaller values, thus reducing their footprint and height.

### Simple structure of a battery-powered chip



We aim to design a converter that will be integrated inside the digital chip. It will allow a granular power management of the digital chip, and reduce the constraints of the on-board DC-DC converter.

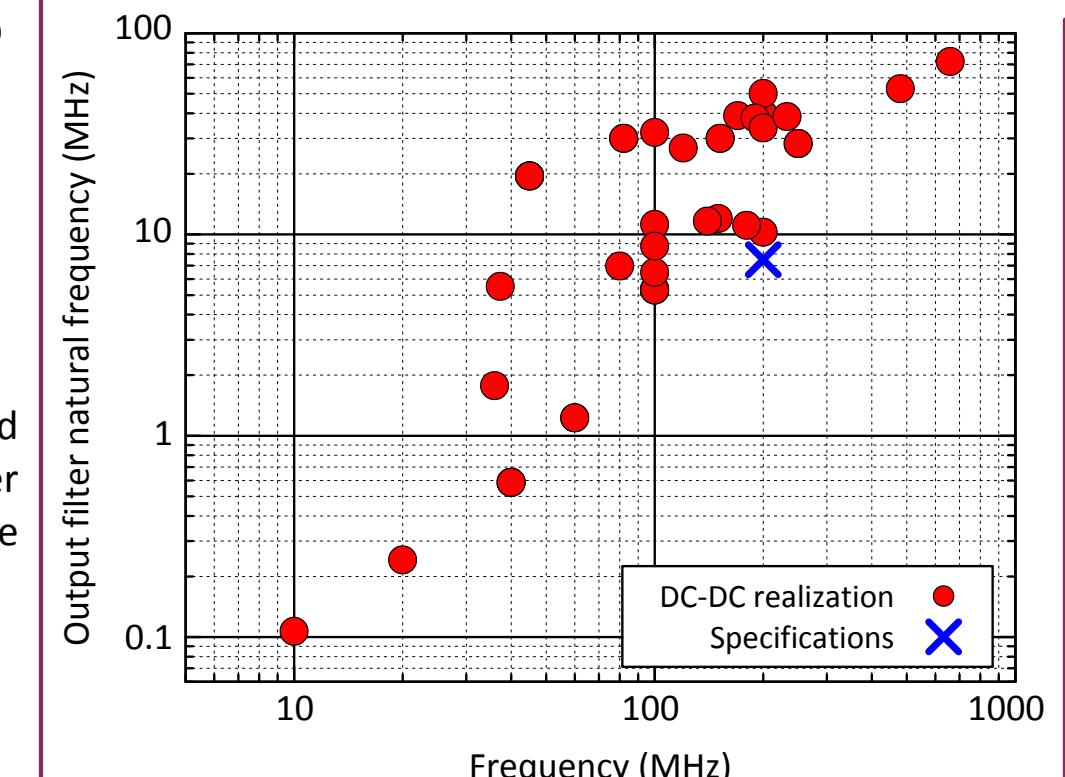
### Cross-section of physical target



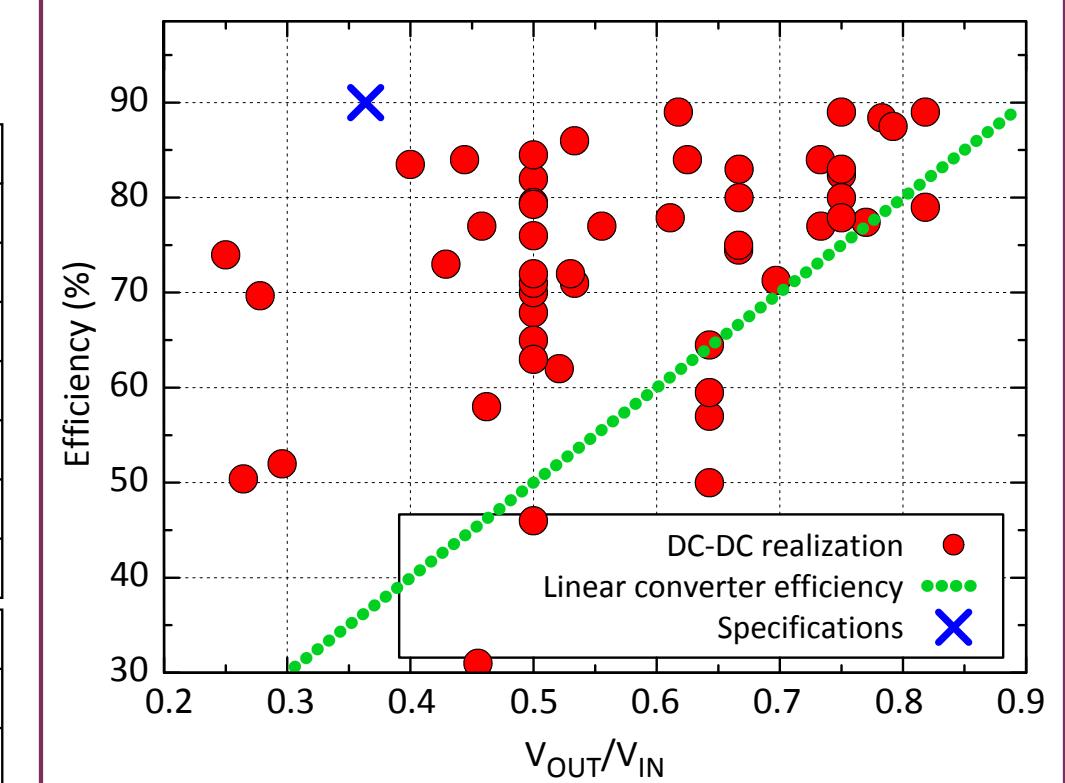
### Specifications summary (nominal)

	Value	Unit
Input voltage	3.3	V
Output voltage	1.2	V
Output current	280	mA
Output power	336	mW
Output voltage ripple	± 2	%
Frequency	100 - 200	MHz
Efficiency	90	%
Active area	≤ 1	mm <sup>2</sup>
Passive area	≤ 10	mm <sup>2</sup>
Total area	≤ 10	mm <sup>2</sup>
Height	≤ 1.2	mm
Technology	40	nm

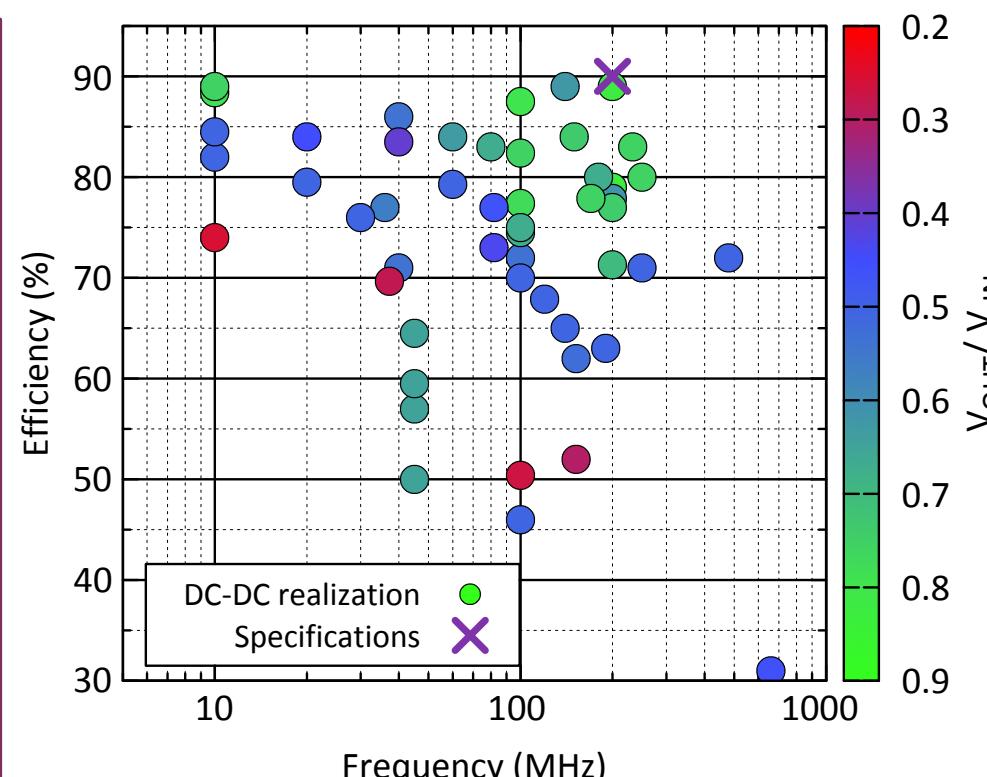
## State-of-the-art - Low power, high frequency, non-isolated converters



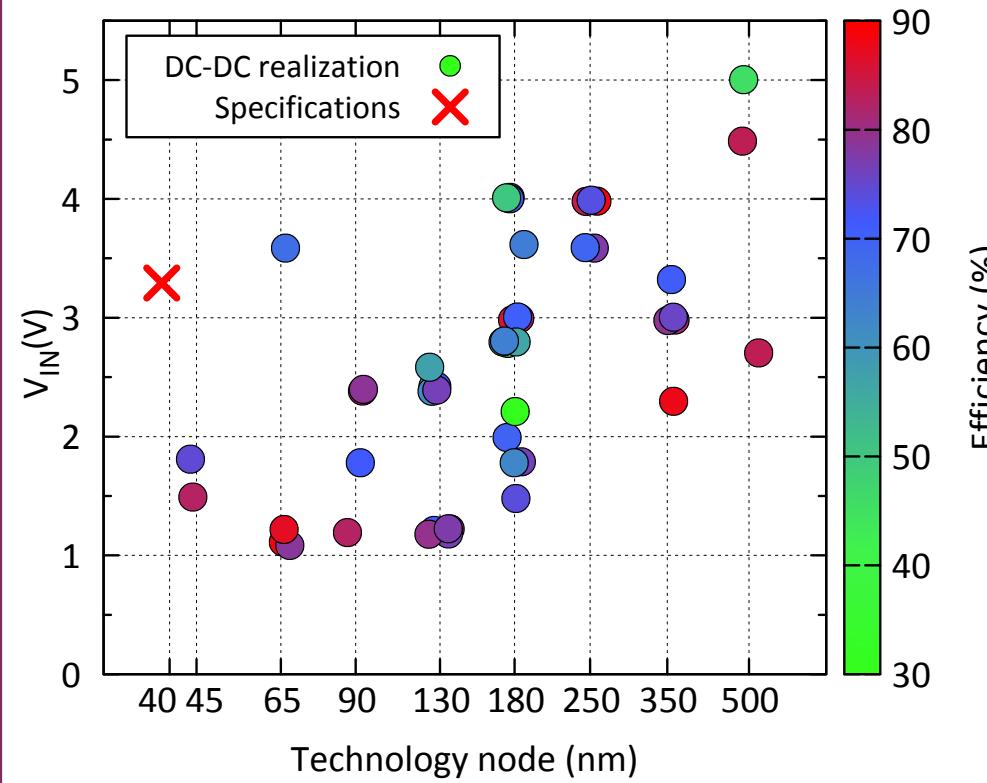
Frequency ↗ ⇒ Filter values ↘



Ratio ↗ ⇒ Efficiency ↗



Frequency ↗ ⇒ Efficiency ↘

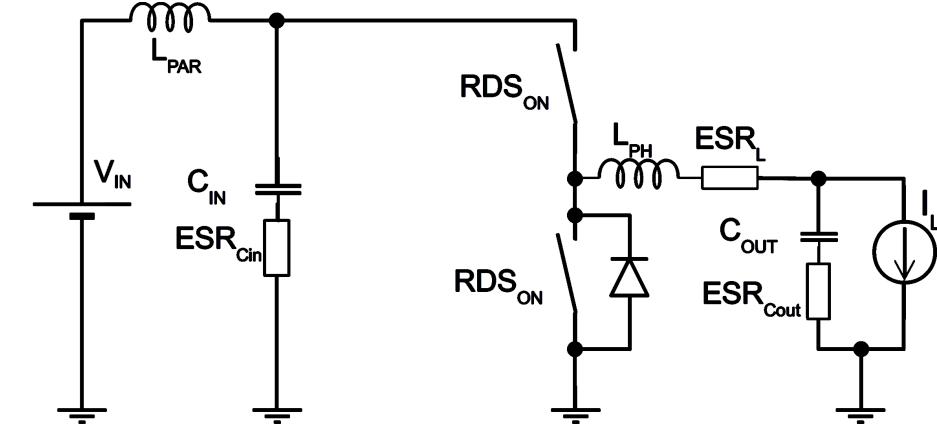


Technology ↗ ⇒ Input voltage ↘

## Architecture evaluation - High level analysis

Conditions de simulation:  
 $V_{IN} = 3.3 \text{ V}$ ;  $V_{OUT} = 1.2 \text{ V}$ ;  $I_{LOAD} = 280 \text{ mA}$ ;  $L_{PH} = 50 \text{ nH}$ ;  $ESR_L = 50 \text{ m}\Omega$ ;  $C_{IN} = 250 \text{ nF}$ ;  $ESR_{CIN} = 250 \text{ m}\Omega$   
 $C_{OUT} = 250 \text{ nF}$ ;  $ESR_{COUT} = 250 \text{ m}\Omega$ ;  $RDS_{ON} = 500/1000 \text{ m}\Omega$ ;  $F_{SW} = 200 \text{ MHz}$

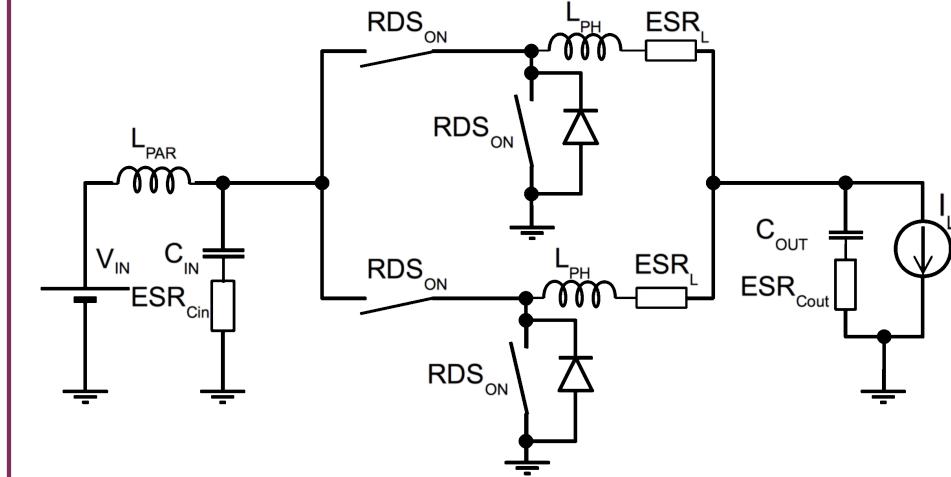
### Standard buck



Efficiency: 79.4 %

Reference design

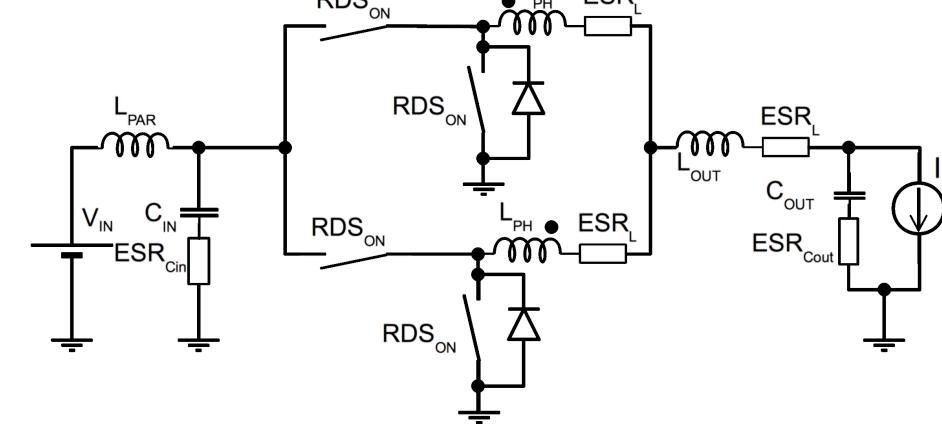
### 2-phases buck



Efficiency: 81.5 %

Slight improvement compared to reference

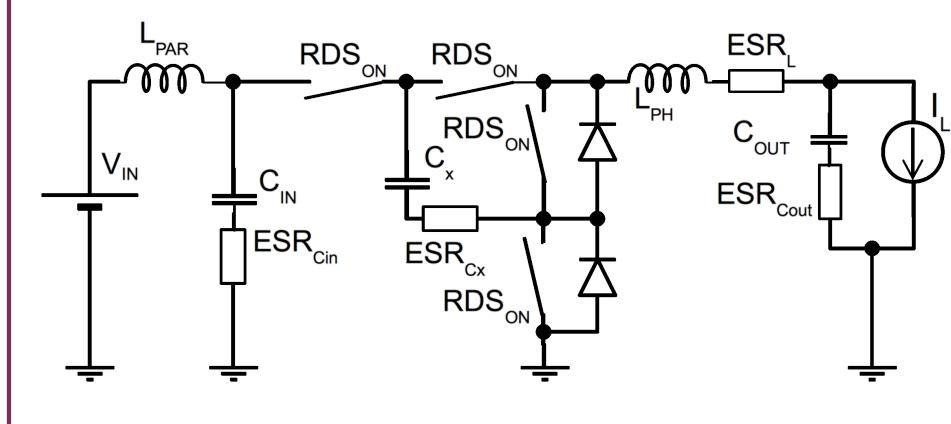
### 2-phases coupled buck



Efficiency: 85.5 %

Good improvement compared to reference

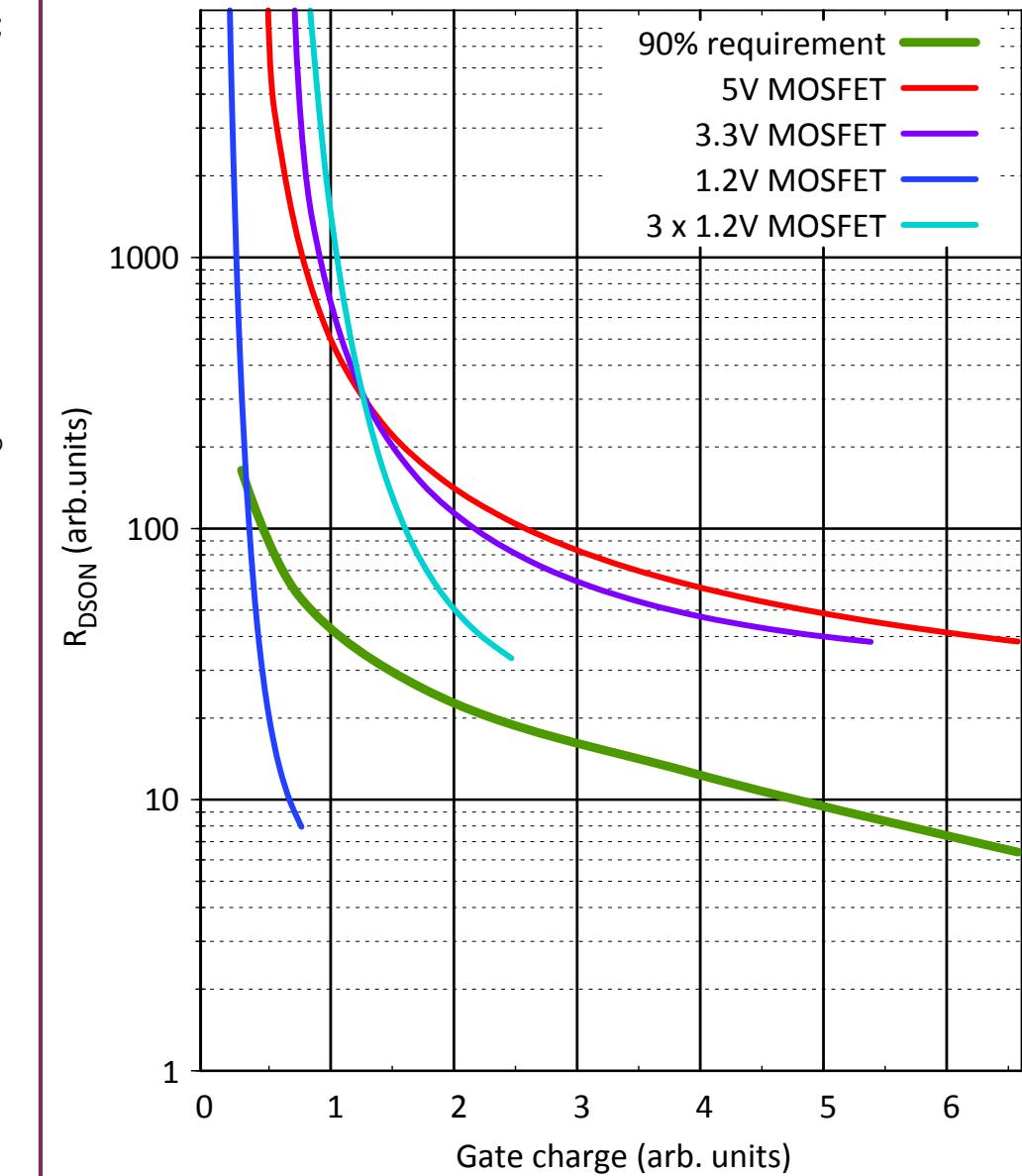
### 3-levels converter



Efficiency: 69.4 %

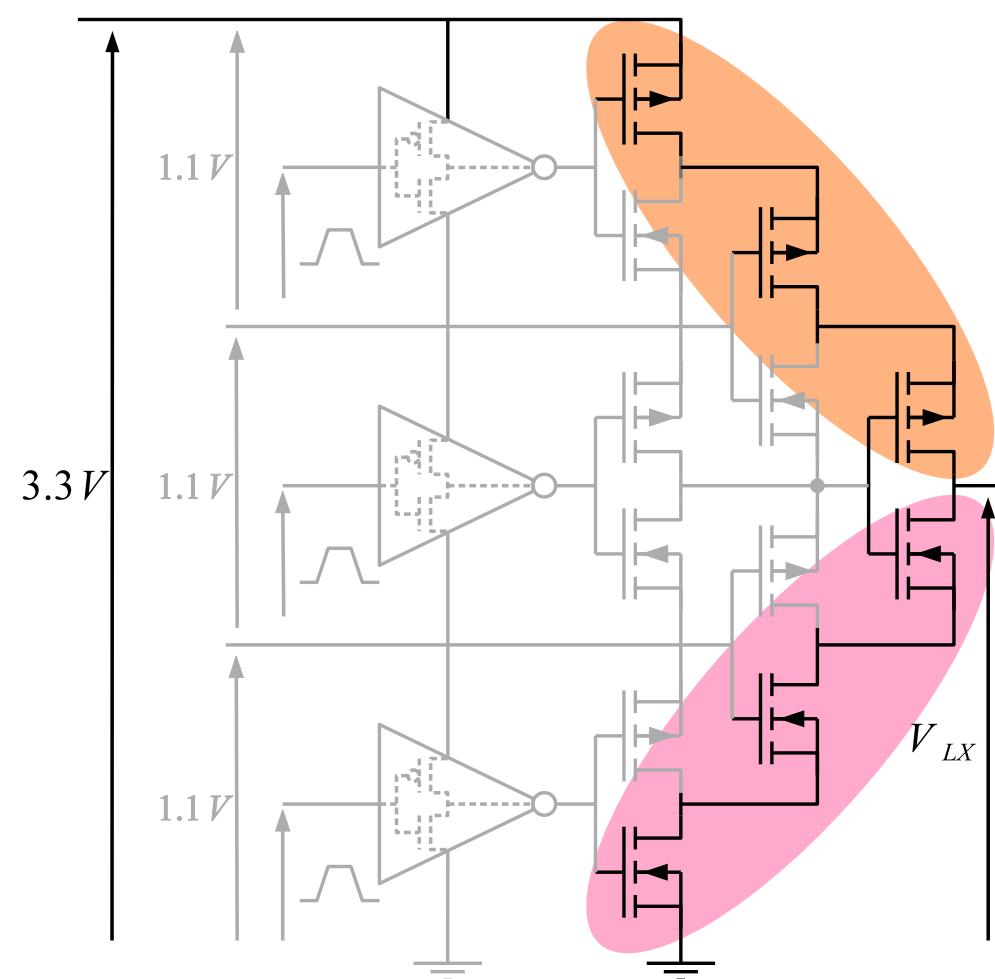
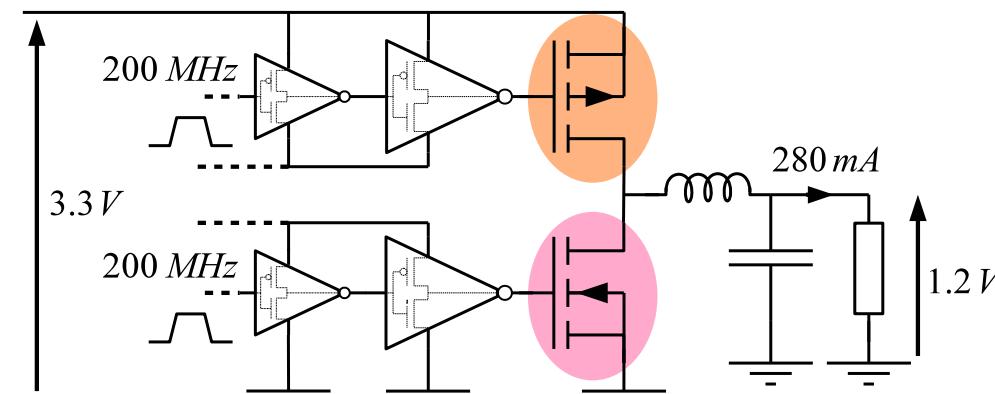
Large degradation compared to reference

## Technology evaluation



- Analysis based on  $R_{DSON} - Q_G$  FOM
- Analysis carried on nominal power point
  - 3.3 V to 1.2 V
  - 280 mA output current
  - 200 MHz switching frequency
- Assuming a standard 1-phase Buck converter
- Only steady-state is considered

Best efficiency can be achieved using low voltage devices associated in series

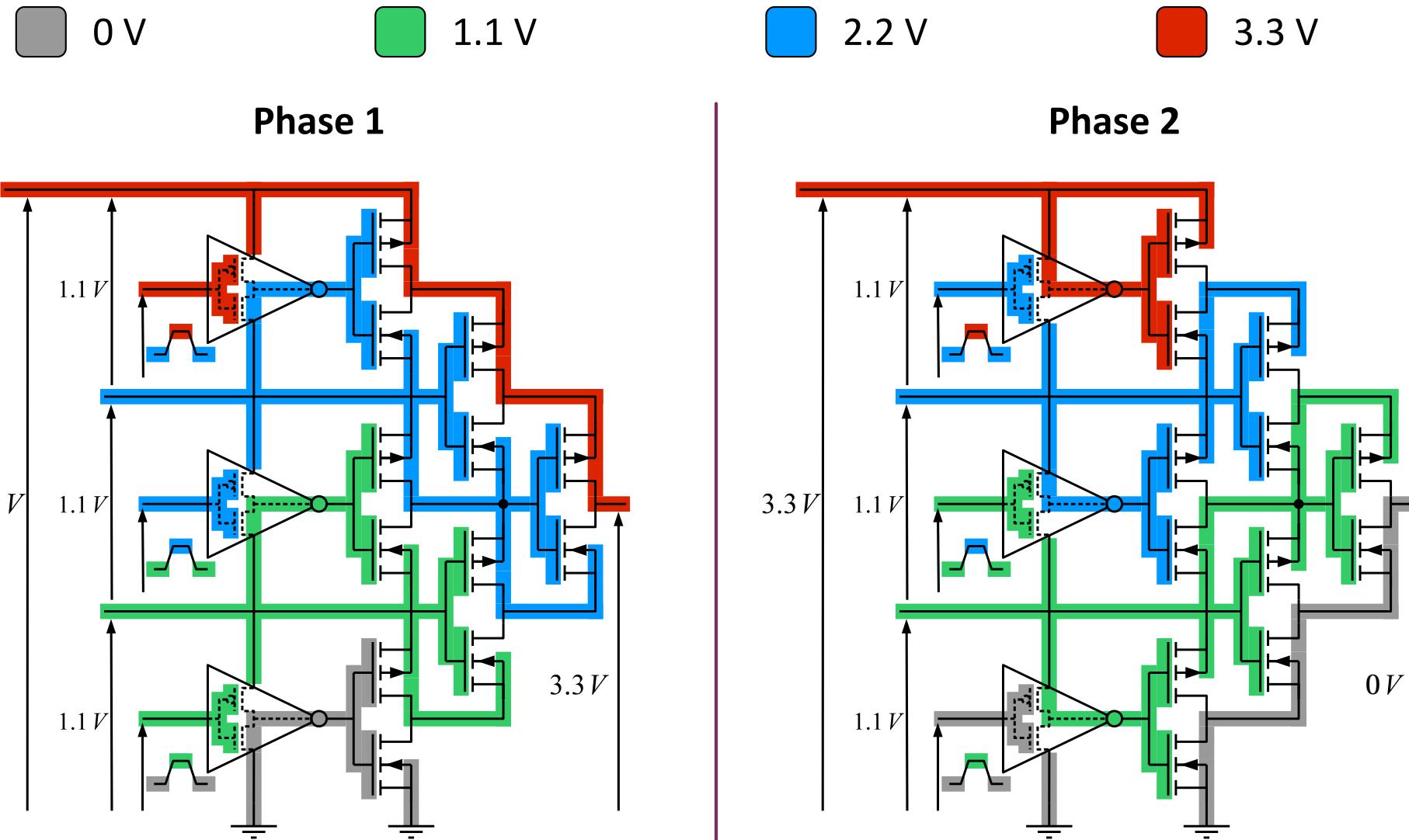


# Power stage design and optimization for low power, high frequency, integrated DC-DC converter

Florian Neveu, University of Lyon, Ampère Lab, France - Bruno Allard, INSA Lyon, Ampère Lab, France - Christian Martin, University of Lyon, Ampère Lab, France - Frédéric Voiron, IPDiA, France

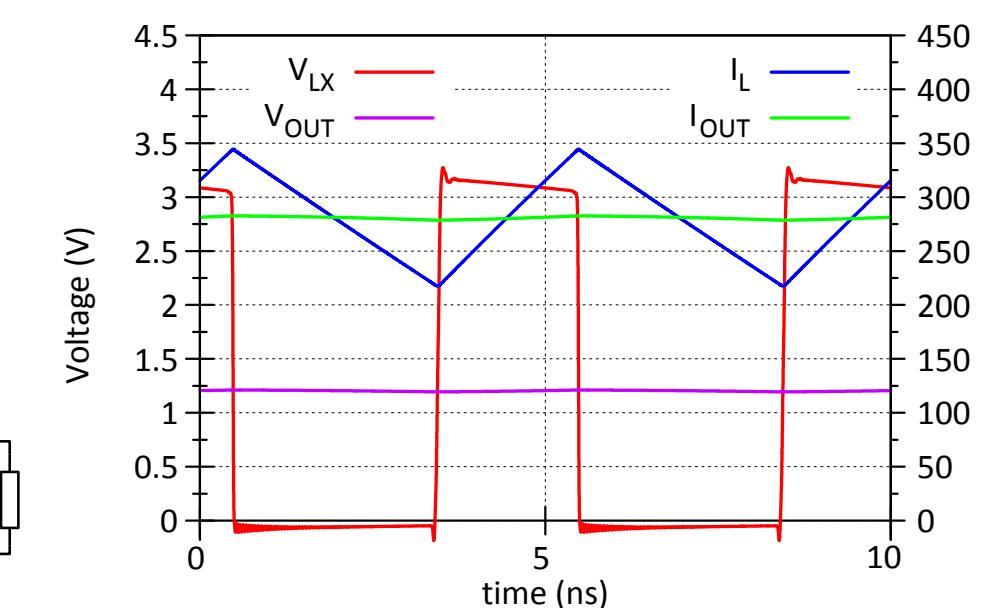
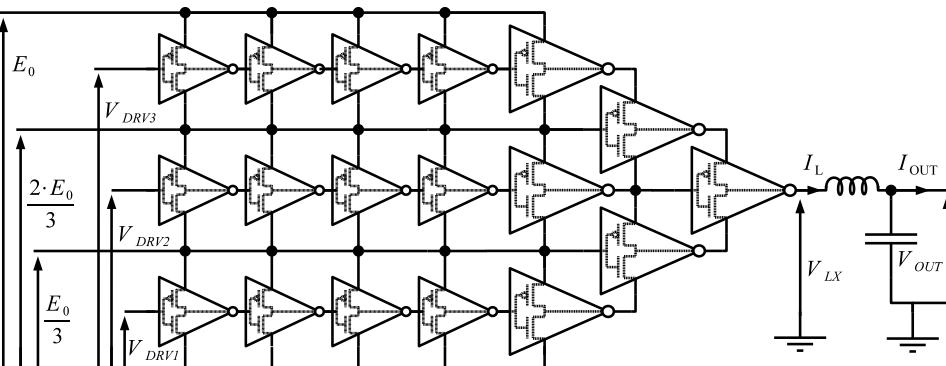


## Cascoded power stage

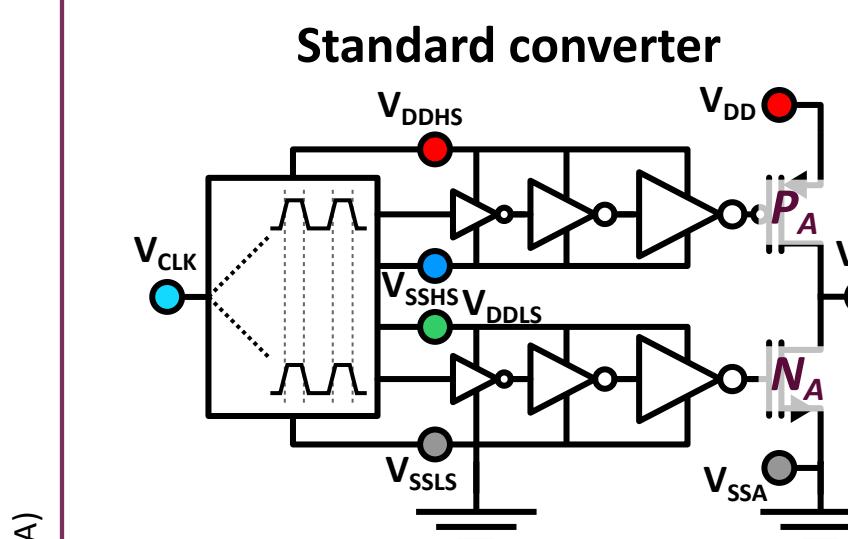
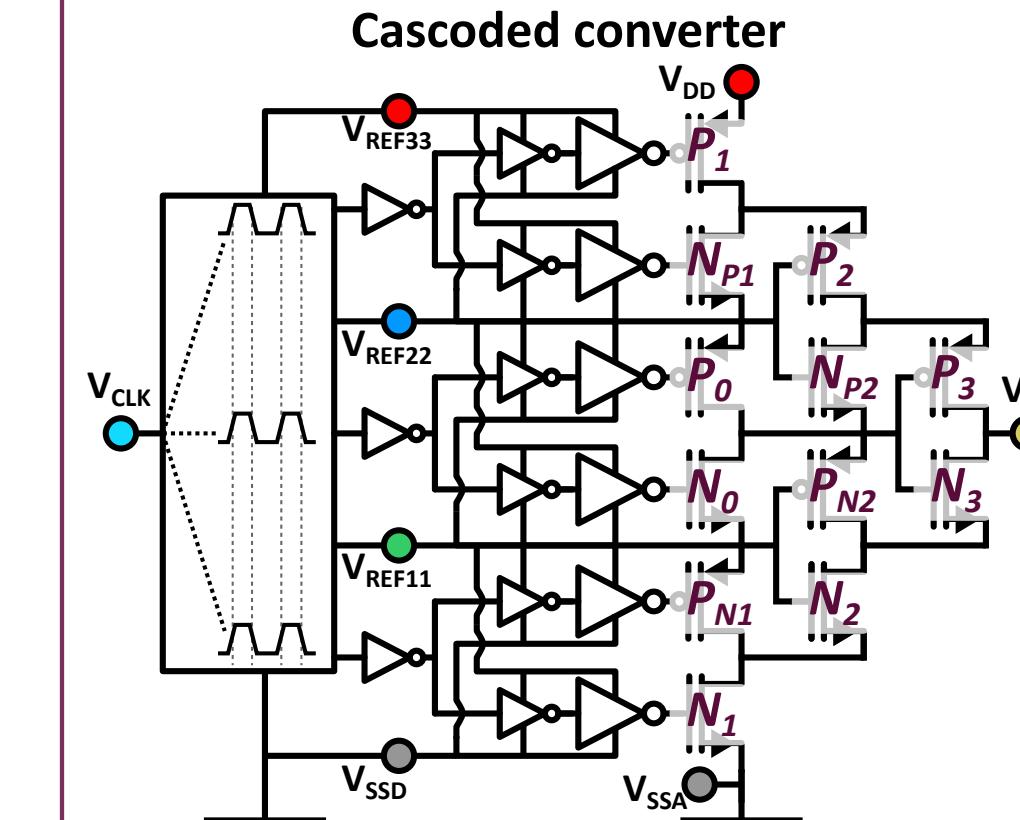


**Simulation waveforms:**  
cascoded power stage in a 1-phase Buck

$$L = 30 \text{ nH}; \quad C_{\text{OUT}} = 15 \text{ nF}; \quad R_{\text{LOAD}} = 4.3 \Omega; \quad E_0 = 3.3 \text{ V}$$



## Optimization - Methodology



- Optimized for various configurations:
  - 200 MHz, nominal power
  - 100 MHz, half nominal power
- All transistors in cascaded power stage have a 40 nm length
- $W_{P1} = W_{P2} = W_{P3}$
- $W_{N1} = W_{N2} = W_{N3}$
- Any other width can vary independently from the others
- Driving signals are synchronized (no skew)
- Optimization also carried out on a standard power stage (3.3 V transistors), as reference
- Optimized in Cadence Virtuoso ADE-XL environment (global optimization)

## Main optimization results

	Standard power stage		Cascoded power stage	
	200 MHz	100 MHz	200 MHz	100 MHz
$W_{P1,2,3}$	-	-	14.8 mm	12.4 mm
$W_{N1,2,3}$	-	-	6 mm	5.4 mm
$W_{PA}$	10.2 mm	7.3 mm	-	-
$W_{NA}$	7.7 mm	4.8 mm	-	-

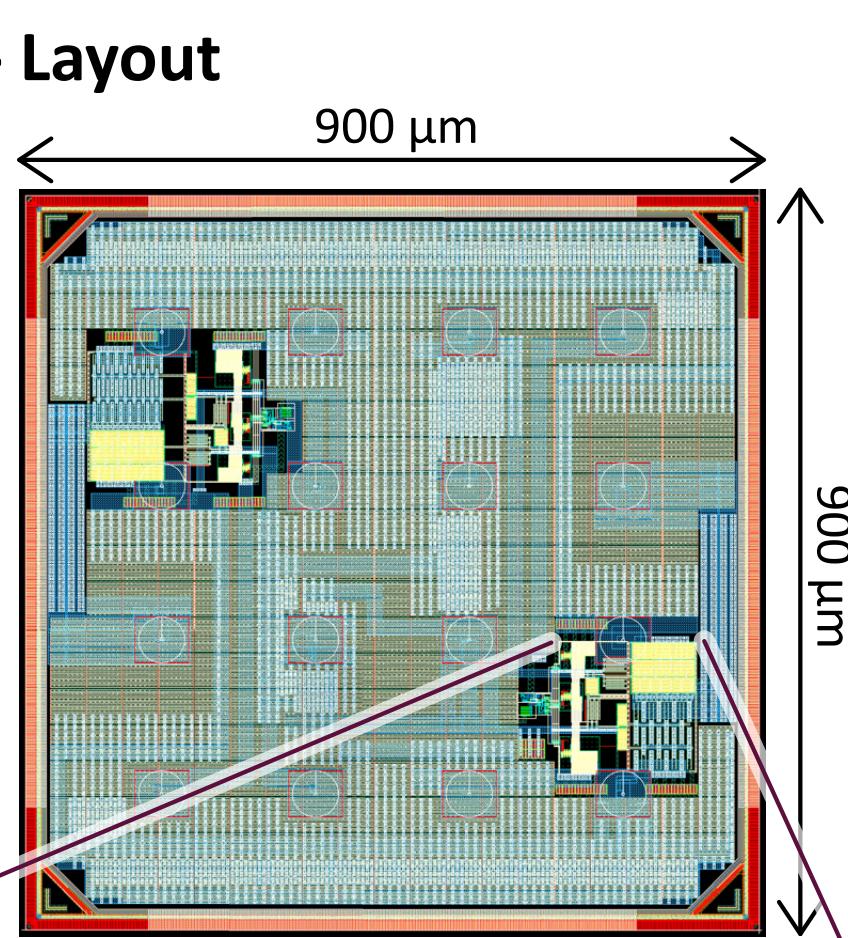
## Efficiency results

	Standard power stage		Cascoded power stage	
	200 MHz	100 MHz	200 MHz	100 MHz
$P_{\text{OUT}}$	336 mW	168 mW	336 mW	168 mW
Efficiency	80.06 %	85.9 %	88.1 %	92.05 %

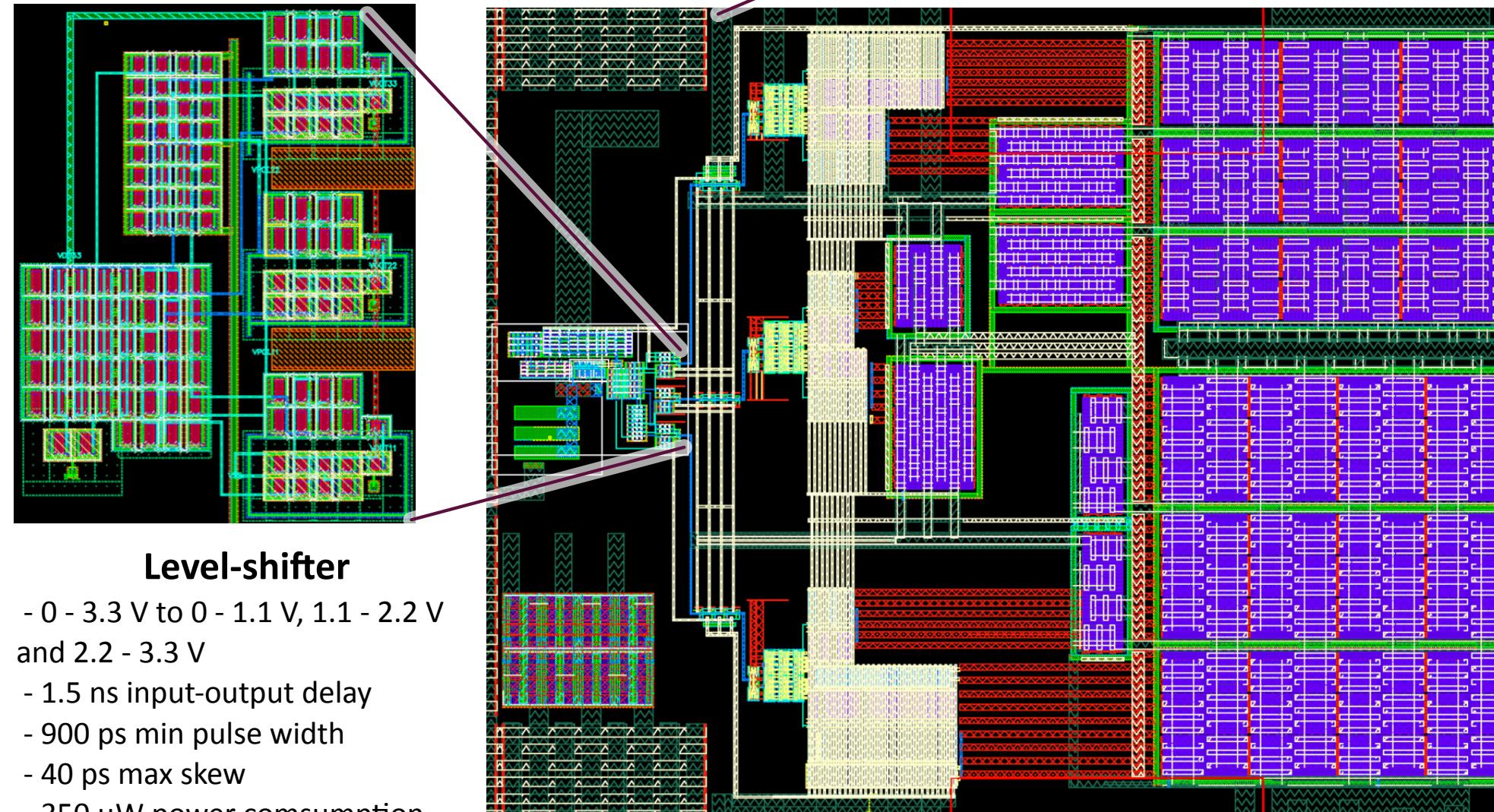
## Implementation - Layout

### Full chip

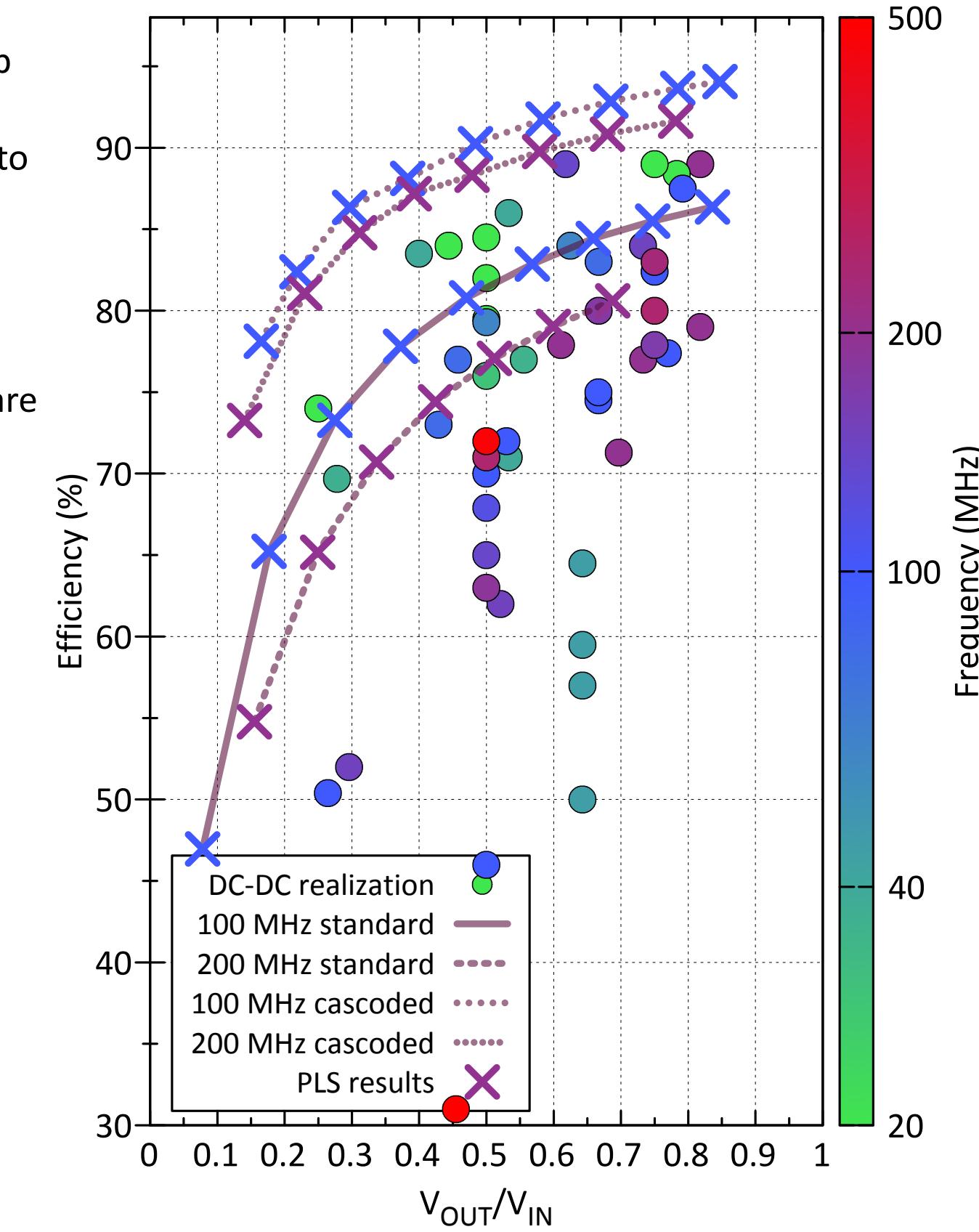
- 2 converters included
  - 200 MHz / 336 mW
  - 100 MHz / 168 mW
- 2 x 8 pads:
  - 1 input power (3.3 V)
  - 3 reference / polarization voltages (1.1, 2.2 and 3.3 V)
  - 1 clock signal
  - 2 grounds (for power and polarisation)
- $\approx 2$  nF on-chip MOM capacitors
  - 1.1 nF for 3.3 V power
  - 3 x 0.3 nF for reference / polarization



### Level-shifter



## Post-layout simulation results

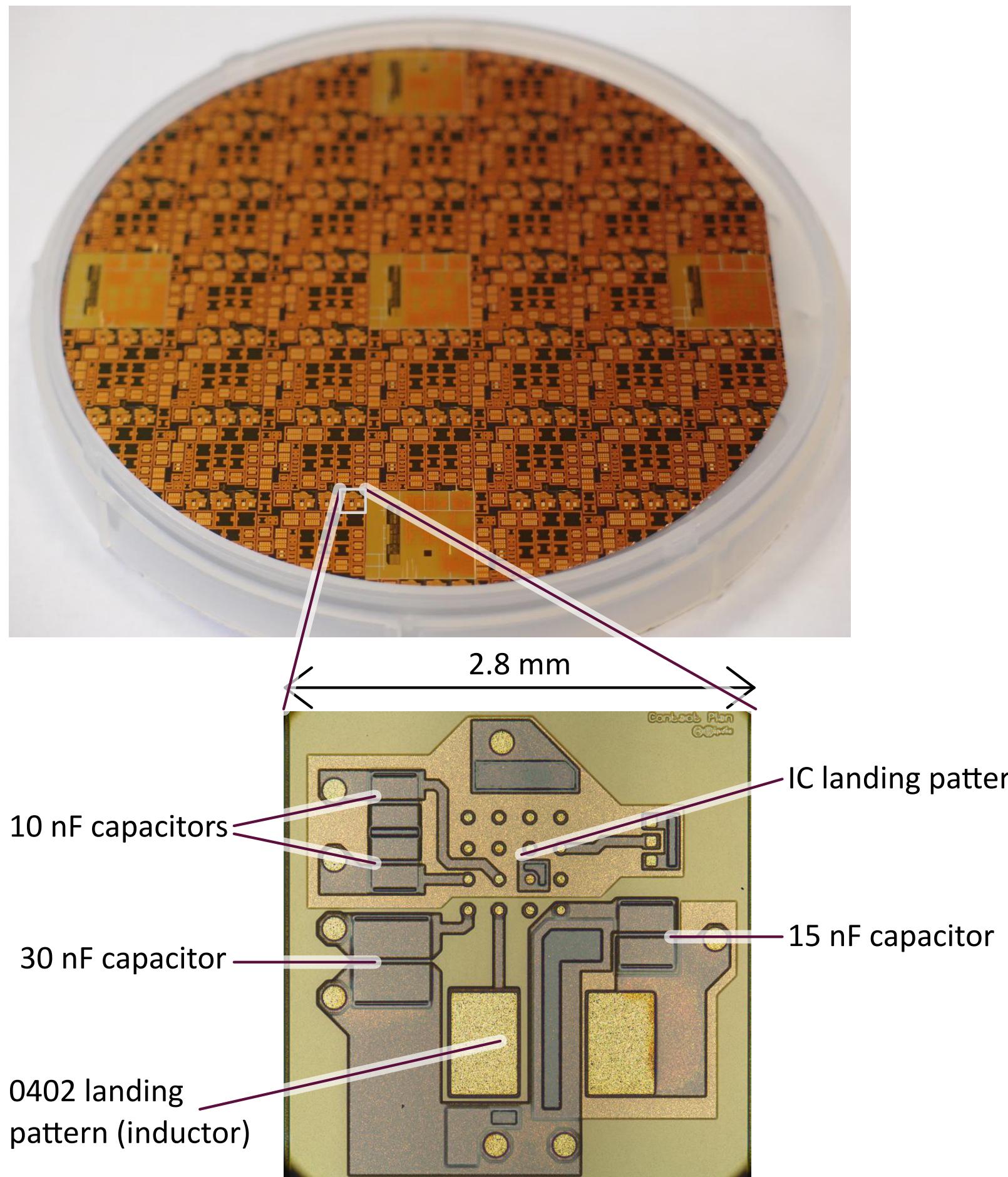


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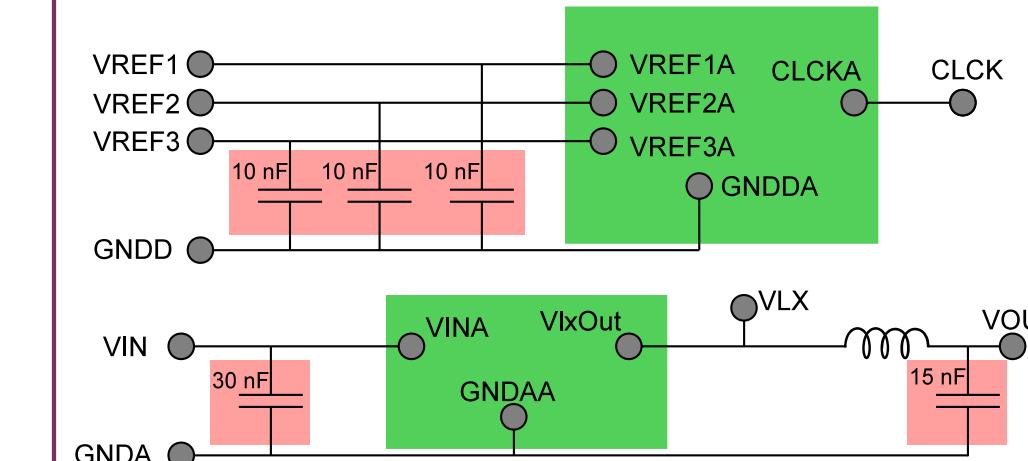


## Interposer - 1<sup>st</sup> prototype



## Interposer - Optimized

### Interposer schematic



### Main changes:

- Routing of GNDA (reducing parasitic inductance) and VLX net
- Adding VREF3 pad and its 10 nF integrated capacitor
- Adding 1 pad for tie up/down of unused IC converter

